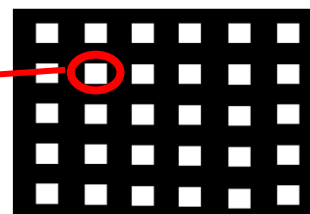
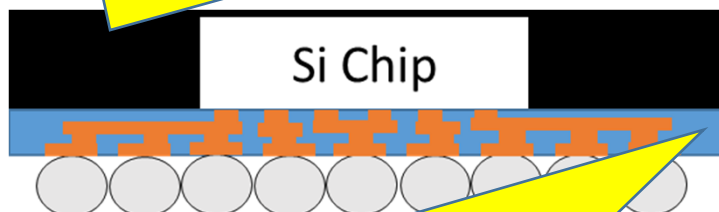
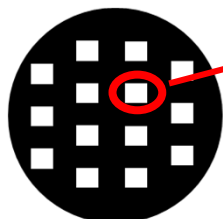


Materials for WLP/PLP

Wafer Level Fan-Out PKG

Panel Level Fan-Out PKG

Liquid Molding Material for Wafer: **MI Series**
 Film Mold Material for Panel: **LE Series**



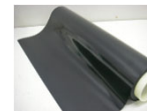
Functional RDL: **Photosensitive dielectrics**

❑ Molding Material

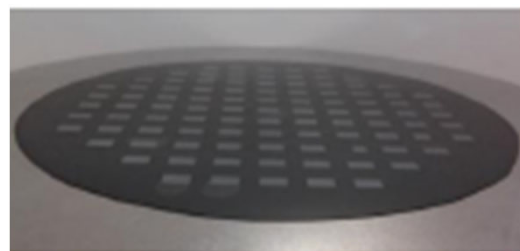
Item	MI Series (Ink Type)	LE Series (Film Type)
Tg (DMA)	171 deg.C	167 deg.C
CTE (30-150deg.C)	7 ppm/K	7 ppm/K
Young's Modulus	8 GPa	7 GPa

MI Series

LE Series



Molding Wafer by MI Series

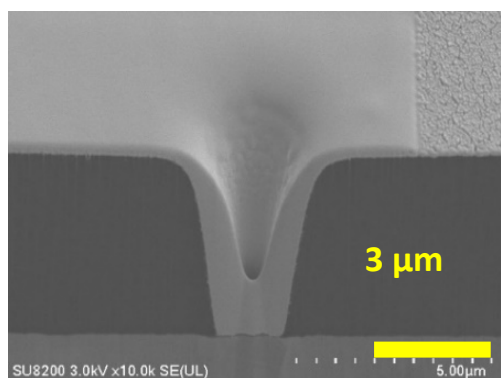


Combination of **Low CTE** and **Low Modulus** is good for lower warpage.

❑ Photosensitive dielectrics

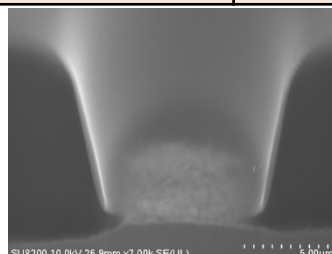
KT-7 series (Film / Liquid type)
 For low temp. curing (190deg.C)

KT-8 series (Film / Liquid type)
 For low temp. curing (200deg.C) with lowDk/Df



3umΦ via on 4.5umt film

CureTemp.	200deg.C	250deg.C
Dk	2.7	2.5
Df	0.0098	0.0059



10umΦ via
 On 11umt film